SOT101-1

plastic dual in-line package; 24 leads (600 mil)

8 February 2016 Package information

1. Package summary

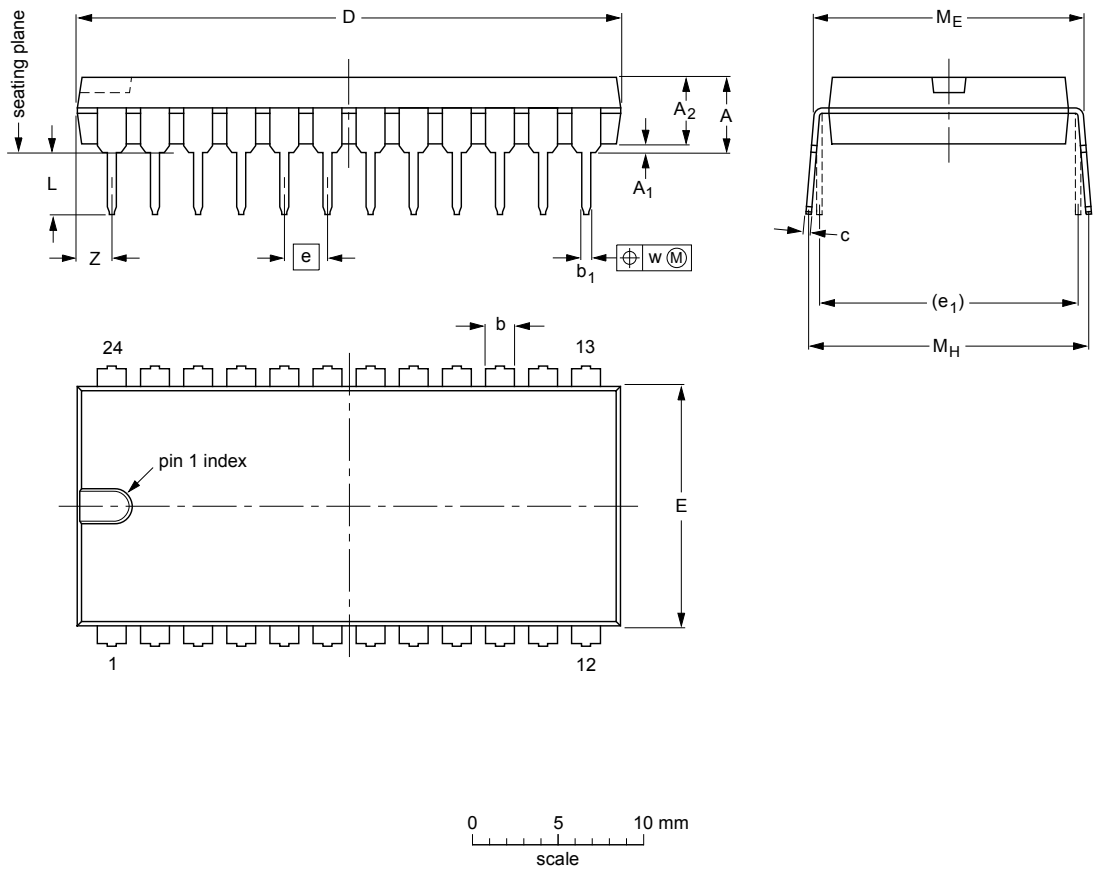
Terminal position code	D (double)
Package type descriptive code	DIP24
Package type industry code	DIP24
Package style descriptive code	DIP (dual in-line package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	051G02
JEDEC package outline code	MO-015
JEITA package outline code	SC-509-24
Mounting method type	T (through-hole mount)
Issue date	13-2-2003

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		31.4	-	31.7	32	mm
E	package width		13.7	-	13.8	14.1	mm
A	seated height		[tbd]	-	5.1	5.1	mm
A_2	package height		[tbd]	-	3.85	4	mm
n_2	actual quantity of termination		-	-	24	-	

2. Package outline

DIP24: plastic dual in-line package; 24 leads (600 mil) **SOT101-1**



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A_1 min.	A_2 max.	b	b_1	c	D (1)	E (1)	e	e_1	L	M_E	M_H	w	Z (1) max.
mm	5.1	0.51	4	1.7 1.3	0.53 0.38	0.32 0.23	32.0 31.4	14.1 13.7	2.54	15.24	3.9 3.4	15.80 15.24	17.15 15.90	0.25	2.2
inches	0.2	0.02	0.16	0.066 0.051	0.021 0.015	0.013 0.009	1.26 1.24	0.56 0.54	0.1	0.6	0.15 0.13	0.62 0.60	0.68 0.63	0.01	0.087

Note

1. Plastic or metal protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT101-1	051G02	MO-015	SC-509-24			~~99-12-27~~ 03-02-13

Fig. 1. Package outline DIP24 (SOT101-1)

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4. Contents

1. Package summary..... 1
2. Package outline..... 2
3. Legal information..... 3

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